

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc14581csw#pbf

(Engineering Calculation)

SOIC WIDE

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**TOTAL MASS (g) : 0.756053**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.010223	1000000	13521.5322266		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.184353	975000	243835.9375		
		Iron (Fe)	7439-89-6	0.004538	24000	6002.22167969		
		Phosphorus (P)	7723-14-0	0.000057	300	75.3915023804		
		Zinc (Zn)	7440-66-6	0.000132	700	174.59085083		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.189080</b>	<b>1000000</b>	<b>250088.15625</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.008359	1000000	11056.5742188		
		<b>External Plating Total:</b>				<b>0.008359</b>	<b>1000000</b>	<b>11056.5742188</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.001513	1000000	2001.18151855		
		<b>Internal Plating Total:</b>				<b>0.001513</b>	<b>1000000</b>	<b>2001.18151855</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.002201	750000	2911.16992188		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000734	250000	970.830932617		
<b>Die Attach Total:</b>				<b>0.002935</b>	<b>1000000</b>	<b>3882.00097656</b>		
Encapsulation	FILLED EPOXY RESIN	Resin (EP)		0.081459	150000	107742.390625		
		Bromine (Br)	40039-93-8	0.005431	10000	7183.35546875		
		Silica (SiO2)	60676-86-0	0.439879	810000	581809.4375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.016292	30000	21548.7421875		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000000	0	0		
		<b>Encapsulation Total:</b>				<b>0.543061</b>	<b>1000000</b>	<b>718283.9375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000882	1000000	1166.58435059		
					<b>TOTAL MASS (g) :</b>	<b>0.756053</b>		